



HW-15-08-G-S-335-SM



OPTION



(2.54 mm) .100"

**HW-SM SERIES** 

 $\mathsf{SM}$ 

**OTHER** 

OPTIONS

# FLEXIBLE .025" SQ BOARD STACKERS

#### **Board Mates:**

SSW, SSQ, ESW, ESQ, CES, SLW, BSW, BCS, SSM, HLE, PHF

Cable Mates:

IDSS, IDSD

#### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?HW-SM

#### **Insulator Material:**

Top: Natural LCP
Bottom: Black LCP
Terminal Material:
Phosphor Bronze
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp Range:
-55 °C to +125 °C with Gold
-55 °C to +105 °C with Tin
RoHS Compliant:

#### **PROCESSING**

Lead-Free Solderable:

#### SMT Lead Coplanarity:

(0.15 mm) .006" max\*
\*(.004" stencil solution
may be available; contact
IPG@samtec.com)

### RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



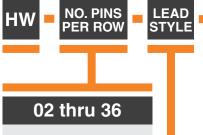
#### ALSO AVAILABLE (MOQ REQUIRED)

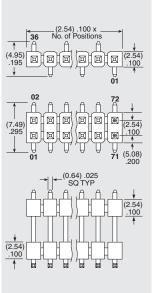
- · Other platings
- Locking Clip (Manual placement required) available with double row –SM

#### Notes:

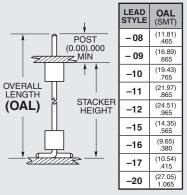
For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact jpg@samtec.com for more information.

This Series is non-standard, non-returnable.





## Specify LEAD STYLE from chart



ROW STACKER HEIGHT

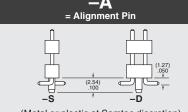






-"XXX"
= Polarized

Specify omitted pin position



(Metal or plastic at Samtec discretion)

—TR = Tape & Reel Packaging (4–27 pins per row only) (Not Available on Lead Styles 10, 11, 12 & 20)

**-F** = Gold flash on contact, Matte Tin on tail

= 10 μ" (0.25 μm) Gold on contact area of longer tail, Matte Tin on tail

—**G** = 10 μ" (0.25 μm) Gold on contact area of longer tail, Gold flash on balance

> — **|** = Matte Tin

Due to technical progress, all designs, specifications and components are subject to change without notice